

Amendments to the Specification:

Please replace the paragraph beginning at page 7, line 6 of the English translation of the specification with the following amended paragraph:

-- The third exemplary embodiment, illustrated in Fig. 3, is a miniature light-emitting diode comprising a flexible leadframe 10, an LED chip 1 with an active, radiation-emitting region, and a molded plastic part 5. Said flexible leadframe 10 is made of 60 μm thick metal foil 101 and 60 μm thick plastic film 102, which are glued together very precisely. The plastic film can be made of silicone plastic. --

Please replace the paragraph beginning at page 7, line 15 of the English translation of the specification with the following amended paragraph:

-- To be able to produce as many components as possible on the flexible frame, the encapsulation is done for example by "cavity-to-cavity molding," as shown in Fig. 4, in which a molded plastic part 5 that encapsulates the LED chip 1 and the bonding wire 2 is fabricated over each flexible leadframe 10. The number of injection channels is reduced by running an injection channel 55 through cavities 50 of the components. The molded plastic part is made of the same material as the molded plastic part of the aforesaid exemplary embodiments. --

Please add the following new paragraph after the paragraph ending at page 4, line 24 of the English translation of the specification:

-- Fig. 4 is a schematic diagram showing an injection channel running between multiple exemplary components. --